

CLAIMS

What is claimed is:

1. An integrated circuit package comprising:
a semiconductor die;
a plurality of conductors, at least some of which are coupled to the semiconductor die; and
at least one alignment feature separate from the plurality of conductors.
2. The integrated circuit package of claim 1, wherein the at least one alignment feature includes at least one aperture.
3. The integrated circuit package of claim 1, wherein the at least one alignment feature is semi-circular shaped.
4. The integrated circuit package of claim 1, further comprising an insulating material encompassing the semiconductor die and a portion of each of the plurality of conductors, the insulating material comprising a first end and a second end, wherein the at least one alignment feature comprises an alignment feature disposed on both the first end and the second end of the insulating material.
5. The integrated circuit package of claim 1, wherein the at least one alignment feature comprises a protuberance.
6. An integrated circuit package comprising:
a semiconductor die;
a plurality of conductors, at least some of which are coupled to the semiconductor die;
at least one alignment feature; and
insulating material encompassing the at least one alignment feature.

7. The integrated circuit package of claim 6, wherein the at least one alignment feature is an alignment cut-out.

8. The integrated circuit package of claim 6, wherein the at least one alignment feature includes at least one aperture.

9. The integrated circuit package of claim 6, wherein the at least one alignment feature is semi-circular shaped.

10. The integrated circuit package of claim 6, wherein the at least one alignment feature comprises a tie bar.

11. The integrated circuit package of claim 6 further comprising a lead frame having a first end and a second end, wherein the at least one alignment feature comprises an alignment feature disposed on both the first end and the second end of the lead frame.

12. The integrated circuit package of claim 6, wherein the at least one alignment feature comprises a protuberance.

13. A lead frame strip ready for cutting, the lead frame strip comprising a plurality of integrated circuit packages, each integrated circuit package comprising:
a semiconductor die;
a plurality of conductors, at least some of which are coupled to the semiconductor die;
insulating material encompassing the semiconductor die and portions of the plurality of conductors; and
at least one alignment feature electrically isolated from the plurality of conductors.